

Specifications

Designed to support applications such as: SOHO (ADSL Modems), LAN-on-Motherboard (LOM), Hub and Switches. Meets IEEE 802.3 specification.

Materials:

- Housing: Thermoplastic UL94V-0
- Contact/Shield: Copper Alloy
- Shield Plating: Nickel
- Contact Plating: Gold 6µ" min. in contact area
- Wave solder tip temperature: 265°C Max for 5 Sec Max

Electrical Specifications @25°C

Operating Temperature Range: 0°C to 70°C

Turn Ratio (±2%):

$$TX = 1CT:1CT, RX = 1CT:1CT$$

Inductance OCL:

$$350\mu H \text{ Min @ } 100KHz, 0.1V, 8mA \text{ DC Bias}$$

Insertion Loss:

$$-1.0dB \text{ Max @ } 1.0-65MHz$$

Return Loss: (@100Ω ± 15Ω)

$$-20dB \text{ Min @ } 1.0-10MHz$$

$$-16dB \text{ Min @ } 10-30MHz$$

$$-12dB \text{ Min @ } 30-60MHz$$

$$-10dB \text{ Min @ } 60-100MHz$$

Cross Talk:

$$-40dB \text{ Min @ } 1.0-30MHz$$

$$-35dB \text{ Min @ } 30-60MHz$$

$$-30dB \text{ Min @ } 60-100MHz$$

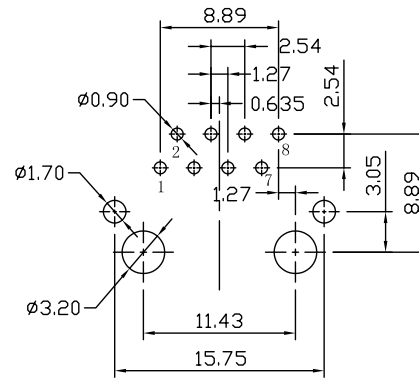
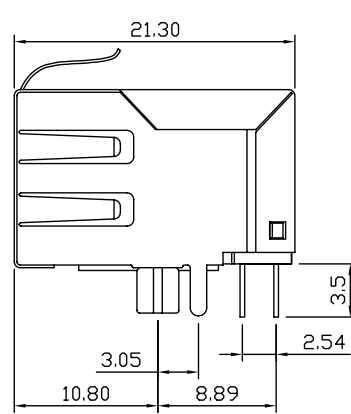
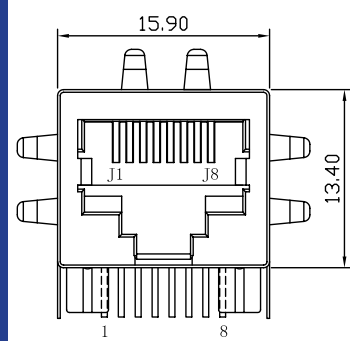
Common Mode Rejection:

$$-30dB \text{ Min @ } 1.0-50MHz$$

$$-20dB \text{ Min @ } 50-150MHz$$

Hipot Test: 1500Vrms Min

General Tolerance	
.X ± 0.30	Angles: ±1°
.XX ± 0.20	
.XXX ± 0.05	
Units : mm	



SUGGESTED PCB LAYOUT (TOP VIEW)

